

Product Features

- DC 4 GHz
- +19 dBm P1dB at 1 GHz
- +34 dBm OIP3 at 1 GHz
- 20 dB Gain at 1 GHz
- 5.5 dB Noise Figure at 2 GHz
- Available in lead-free / green SOT-86 and SOT-89 Package Styles
- Internally matched to 50Ω

Applications

- Mobile Infrastructure
- CATV / DBS
- W-LAN / ISM
- RFID
- Defense / Homeland Security
- Fixed Wireless

Product Description

The EC1019 is a general-purpose buffer amplifier that offers high dynamic range in a low-cost surface-mount package. At 1000 MHz, the EC1019 typically provides 20 dB of gain, +34 dBm Output IP3, and +19 dBm P1dB.

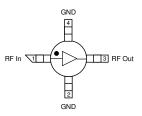
The EC1019 consists of Darlington pair amplifiers using the high reliability InGaP/GaAs HBT process technology and only requires DC-blocking capacitors, a bias resistor, and an inductive RF choke for operation. The device is ideal for wireless applications and is available in low-cost, surface-mountable lead-free/green/RoHS-compliant SOT-86 and SOT-89 packages. All devices are 100% RF and DC tested.

The broadband MMIC amplifier can be directly applied to various current and next generation wireless technologies such as GPRS, GSM, CDMA, and W-CDMA. In addition, the EC1019 will work for other various applications within the DC to 4 GHz frequency range such as CATV and fixed wireless.

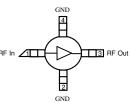
Functional Diagram



EC1019B / EC1019B-G



EC1019C



EC1019C-G

Specifications (1)

Parameter	Units	Min	Тур	Max	
Operational Bandwidth	MHz	DC		4000	
Test Frequency	MHz		1000		
Gain	dB		19.8		
Output P1dB	dBm		+19		
Output IP3 (2)	dBm		+34		
Test Frequency	MHz		2000		
Gain	dB		17.8		
Large-signal Gain (3)	dB	14	14 15.5		
Input Return Loss	dB	19			
Output Return Loss	dB		15		
Output P1dB	dBm		+19.5		
Output IP3 (2)	dBm		+31		
Noise Figure	dB		5.5		
Device Voltage	V	4.2	5.0	5.2	
Device Current	mA		70		

^{1.} Test conditions unless otherwise noted: 25° C, Supply Voltage = +6 V, Rbias = 16.5 Ω , 50 Ω

Absolute Maximum Rating

Parameter	Rating
Operating Case Temperature	-40 to +85 °C
Storage Temperature	-55 to +150 °C
Device Current	130 mA
RF Input Power (continuous)	+12 dBm
Junction Temperature	+250 °C

Operation of this device above any of these parameters may cause permanent damage.

Typical Performance (4)

Parameter	Units	Typical						
Frequency	MHz	500	900	1900	2140			
S21	dB	21	19.8	18.2	17.5			
S11	dB	-17	-18	-19	-20			
S22	dB	-15	-15	-15	-15			
Output P1dB	dBm	+19	+19	+19.5	+19			
Output IP3 (2)	dBm	+34	+34	+31	+31			
Noise Figure	dB	3.8	4.0	4.8	5.5			

^{4.} Test conditions: T = 25° C, Supply Voltage = +6 V, Device Voltage = +5 V, R_{bias} = 16.5 Ω , 50 Ω System.

Ordering Information

Part No.	Description
EC1019B*	InGaP HBT Gain Block (lead-tin SOT-89 Pkg)
EC1019B-G	InGaP HBT Gain Block (lead-free/green/RoHS-compliant SOT-89 Pkg)
EC1019C*	InGaP HBT Gain Block (lead-tin SOT-86 Pkg)
EC1019C-G	InGaP HBT Gain Block (lead-free/green/RoHS-compliant SOT-86 Pkg)
EC1019B-PCB	700 – 2400 MHz Fully Assembled Eval. Board
EC1019C-PCB	700 – 2400 MHz Fully Assembled Eval. Board

This package is being phased out in favor of the green package type which is backwards compatible for existing designs. Refer to Product Change Notification WJPCN06MAY05TC1 on the WJ website

^{2. 3}OIP measured with two tones at an output power of +4 dBm/tone separated by 1 MHz. The

suppression on the largest IM3 product is used to calculate the 3OIP using a 2:1 rule. 3. Large-signal gain is tested with an input power level of +4 dBm.

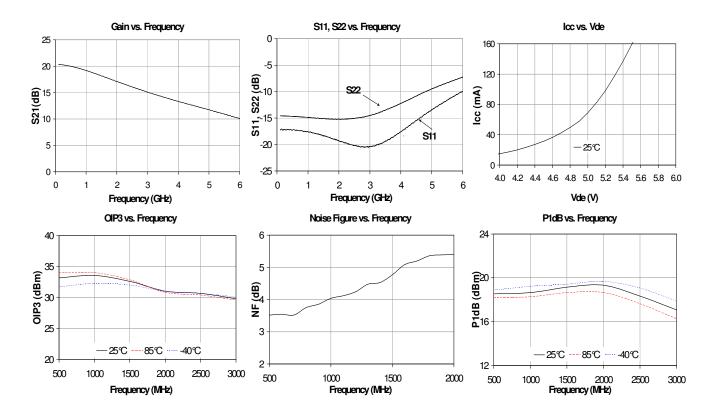


Typical Device RF Performance Supply Bias = +6 V, R_{bias} = 14 Ω , I_{cc} = 70 mA

Frequency	MHz	100	500	900	1900	2140	2400	3500	5800
S21	dB	20.4	20.0	19.8	18	17.5	16.8	14.2	10.3
S11	dB	-17	-17	-18	-19	-20	-20	-19	-11
S22	dB	-15	-15	-15	-15	-15	-15	-14	-7.7
Output P1dB	dBm	+19.4	+19.4	+19.4	+19.5	+19.0	+18.8	+16.2	
Output IP3	dBm	+33	+33.2	+33.6	+31	+31	+30.7		
Noise Figure	dB	3.4	3.8	4.0	4.8	5.5			

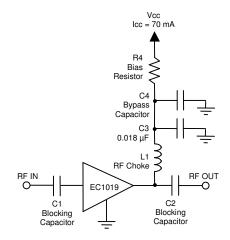
- 1. Test conditions: T = 25° C, Supply Voltage = +6 V, Device Voltage = 5.0 V, Rbias = 16.5 Ω , Icc = 70 mA typical, 50 Ω System.
- 2. 3OIP measured with two tones at an output power of +4 dBm/tone separated by 1 MHz. The suppression on the largest IM3 product is used to calculate the 3OIP using a 2:1 rule.

 3. Data is shown as device performance only. Actual implementation for the desired frequency band will be determined by external components shown in the application circuit.

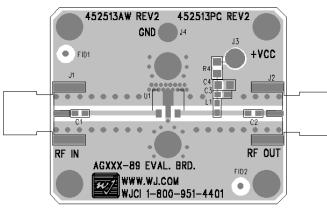




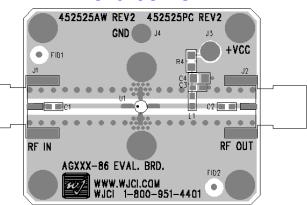
Recommended Application Circuit



EC1019B-PCB



EC1019C-PCB



Recommended Component Values

Reference	Frequency (MHz)							
Designator	50	500	900	1900	2200	2500	3500	
L1	820 nH	220 nH	68 nH	27 nH	22 nH	18 nH	15 nH	
C1, C2, C4	.018 µF	1000 pF	100 pF	68 pF	68 pF	56 pF	39 pF	

- 1. The proper values for the components are dependent upon the intended frequency of operation.
- 2. The following values are contained on the evaluation board to achieve optimal broadband performance:

Ref. Desig.	Value / Type	Size
L1	39 nH wirewound inductor	0603
C1, C2	56 pF chip capacitor	0603
C3	0.018 μF chip capacitor	0603
C4	Do Not Place	
R4	14 Ω 1% tolerance	0805

Recommended Bias Resistor Values

Supply Voltage	R1 value	Size
6 V	16.4 ohms	0805
7 V	30.7 ohms	1210
8 V	45 ohms	1210
9 V	59 ohms	2010
10 V	74 ohms	2010
12 V	102 ohms	2512

The proper value for R1 is dependent upon the supply voltage and allows for bias stability over temperature. WJ recommends a minimum supply bias of +6 V. A 1% tolerance resistor is recommended.

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Product In formation

Application

ESD sensitive device.

Passes between 250 and 500V Human Body Model (HBM) JEDEC Standard JESD22-A114

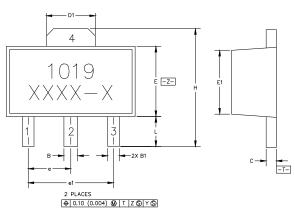
Rating: Level 3 at +235° C convection reflow

JEDEC Standard J-STD-020

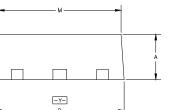
EC1019B (SOT-89 Package) Mechanical Information

This package may contain lead-bearing materials. The plating material on the leads is Sn

Outline Drawing



SYMBOL	MIN	MAX	
А	1.40 (.055)	1.60 (.063)	
В	.44 (.017)	.56 (.022)	
B1	.36 (.014)	.48 (.019)	
С	.35 (.014)	.44 (.017)	
D	4.40 (.173)	4.60 (.181)	
D1	1.62 (.064)	1.83 (.072)	
E	2.29 (.079)	2.60 (.102)	
E1	2.13 (.084)	2.29 (.090)	
e		BSC 59)	١.
e1		BSC 18)	L(
н	3.94 (.155)	4.25 (.167)	⋰
L	.89 (.035)		
м	4.04		V.



- - DIMENSIONS ARE EXPRESSED IN MILLIN
- 3. DIMENSIONING AND TOLERANCING

Mounting Config. Notes

- 1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- 2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal
- 3. Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via region contacts the heatsink.
- 4. Do not put solder mask on the backside of the PC board in the region where the board contacts the heatsink.
- 5. RF trace width depends upon the PC board material and construction.
- 6. Use 1 oz. Copper minimum.
- 7. All dimensions are in millimeters (inches). Angles are in degrees.

Land Patt 0

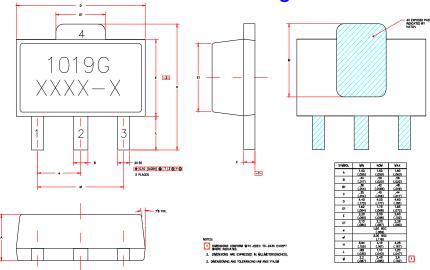
Specifications and information are subject to change without notice



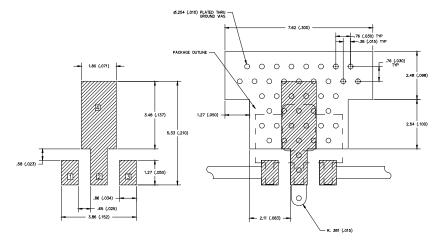
EC1019B-G (Green / Lead-free SOT-89 Package) Mechanical Information

This package is lead-free/Green/RoHS-compliant. It is compatible with both lead-free (maximum 260°C reflow temperature) and leaded (maximum 245°C reflow temperature) soldering processes. The plating material on the leads is NiPdAu.

Outline Drawing



Land Pattern



Product Marking

The component will be marked with an "1019G" designator with an alphanumeric lot code on the top surface of the package.

Tape and reel specifications for this part are located on the website in the "Application Notes" section.

MSL / ESD Rating



Caution! ESD sensitive device.

ESD Rating: Class 1A

Value: Passes between 250 and 500V
Test: Human Body Model (HBM)
Standard: JEDEC Standard JESD22-A114

MSL Rating: Level 3 at +260° C convection reflow Standard: JEDEC Standard J-STD-020

Mounting Config. Notes

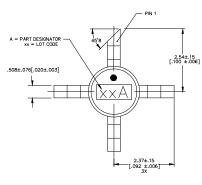
- 1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via region contacts the heatsink.
- 4. Do not put solder mask on the backside of the PC board in the region where the board contacts the heatsink.
- 5. RF trace width depends upon the PC board material and construction.
- 6. Use 1 oz. Copper minimum.
- All dimensions are in millimeters (inches). Angles are in degrees.

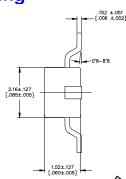
Product Information

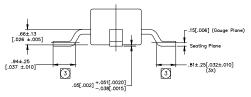
EC1019C (SOT-86 Package) Mechanical Information

This package may contain lead-bearing materials. The plating material on the leads is SnPb.

Outline Drawing







NOTES:

- A. TOLERANO

MSL SSD Rating

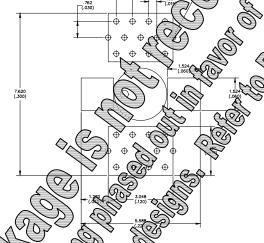
ion! ESD sensitive device.

this part are 'Application

Passes between 250 and 500V Human Body Model (HBM) ard: JEDEC Standard JESD22-A114

MSL Rating: Level 1 at +235° C convection reflow Standard: JEDEC Standard J-STD-020

Land Pattern



Mounting Config. Notes

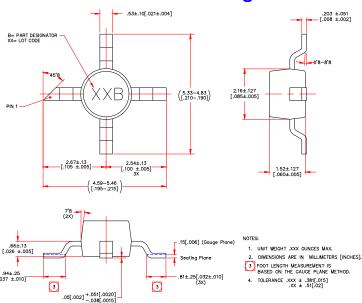
- 1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via region contacts the heatsink.
- Do not put solder mask on the backside of the PC board in the region where the board contacts the heatsink.
- 5. RF trace width depends upon the PC board material and construction.
- 6. Use 1 oz. Copper minimum.
- 7. All dimensions are in millimeters (inches). Angles are in degrees.



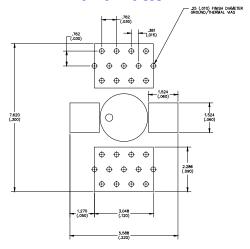
EC1019C-G (Green / Lead-free Sot-86 Package) Mechanical Information

This package is lead-free/Green/RoHS-compliant. It is compatible with both lead-free (maximum 260°C reflow temperature) and leaded (maximum 245°C reflow temperature) soldering processes. The plating material on the pins is annealed matte tin over copper.

Outline Drawing



Land Pattern



Product Marking

The component will be marked with a twodigit numeric lot code (shown as "XX") followed by a "B" designator on the top surface of the package.

Tape and reel specifications for this part are located on the website in the "Application Notes" section.

MSL / ESD Rating



Caution! ESD sensitive device.

ESD Rating: Class 1A

Value: Passes between 250 and 500V Test: Human Body Model (HBM) JEDEC Standard JESD22-A114 Standard:

MSL Rating: Level 3 at +260° C convection reflow JEDEC Standard J-STD-020 Standard:

Mounting Config. Notes

- 1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- 2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.

 Mounting screws can be added near the part to fasten the board
- to a heatsink. Ensure that the ground / thermal via region contacts the heatsink.
- 4. Do not put solder mask on the backside of the PC board in the region where the board contacts the heatsink.

 5. RF trace width depends upon the PC board material and
- construction.
- 6. Use 1 oz. Copper minimum.
- 7. All dimensions are in millimeters (inches). Angles are in



Typical Device S-Parameters – EC1019B / EC1019B-G

S-Parameters ($V_{device} = +5 \text{ V}$, $I_{CC} = 70 \text{ mA}$, $T = 25^{\circ}\text{C}$, calibrated to device leads)

Freq (MHz)	S11 (dB)	S11 (ang)	S21 (dB)	S21 (ang)	S12 (dB)	S12 (ang)	S22 (dB)	S22 (ang)
50	-38.22	-0.60	21.22	176.90	-23.21	0.43	-24.92	-6.19
500	-28.54	-69.70	20.70	151.10	-22.91	1.81	-20.21	-75.88
1000	-23.03	-116.73	19.85	125.62	-22.19	1.88	-15.95	-118.31
1500	-19.80	-149.18	18.77	102.16	-21.39	-0.54	-13.31	-148.47
2000	-16.95	-175.69	17.78	81.09	-20.49	-4.57	-11.44	-173.35
2500	-14.97	161.78	16.64	60.78	-19.66	-10.52	-10.17	164.24
3000	-13.14	141.18	15.54	42.33	-18.91	-17.61	-8.90	144.05
3500	-11.43	120.25	14.52	24.29	-18.40	-26.33	-7.88	125.10
4000	-9.78	100.23	13.50	6.80	-17.96	-35.09	-6.74	107.67
4500	-8.16	82.20	12.43	-10.58	-17.71	-44.95	-5.73	90.92
5000	-6.60	65.82	11.31	-27.02	-17.58	-54.92	-4.75	76.11
5500	-5.40	50.97	10.10	-42.90	-17.72	-64.25	-3.97	61.95
6000	-4.36	38.35	8.93	-58.04	-17.94	-73.51	-3.35	49.09

Typical Device S-Parameters – EC1019C / EC1019C-G

S-Parameters ($V_{device} = +5$, $I_{CC} = 70$ mA, T = 25°C, calibrated to device leads)

Freq (MHz)	S11 (dB)	S11 (ang)	S21 (dB)	S21 (ang)	S12 (dB)	S12 (ang)	S22 (dB)	S22 (ang)
50	-17.33	-1.31	20.43	177.50	-22.79	-0.64	-14.48	-3.98
500	-17.25	-10.41	19.97	155.09	-22.66	4.13	-14.68	-34.98
1000	-17.56	-23.16	19.18	132.71	-22.29	7.47	-14.89	-66.22
1500	-18.41	-38.16	18.15	112.72	-21.69	9.85	-15.11	-93.82
2000	-19.28	-59.40	17.14	94.96	-20.89	10.97	-15.17	-120.65
2500	-20.21	-85.13	16.08	78.76	-20.18	10.33	-15.08	-144.97
3000	-20.40	-116.07	15.09	64.36	-19.45	8.87	-14.49	-168.42
3500	-19.31	-148.51	14.19	50.13	-18.76	5.64	-13.50	169.49
4000	-17.60	-175.60	13.37	36.77	-18.13	1.90	-12.22	151.45
4500	-15.46	161.94	12.54	23.49	-17.57	-2.80	-10.85	136.31
5000	-13.33	142.40	11.78	10.37	-17.10	-8.33	-9.46	123.24
5500	-11.61	126.05	10.94	-2.97	-16.77	-14.35	-8.31	111.67
6000	-9.93	111.47	10.05	-15.41	-16.55	-20.52	-7.23	100.94

Device S-parameters are available for download off of the website at: http://www.wj.com